

## 1.5A Dual High-Speed Power MOSFET Drivers

#### Features:

- High Peak Output Current 1.5A
- Wide Input Supply Voltage Operating Range:
  - 4.5V to 18V
- High Capacitive Load Drive Capability 1000 pF in 25 ns (typ.)
- Short Delay Times 30 ns (typ.)
- · Matched Rise, Fall and Delay Times
- Low Supply Current:
  - With Logic '1' Input 1 mA (typ.)
  - With Logic '0' Input 100 μA (typ.)
- Low Output Impedance  $7\Omega$  (typ.)
- Latch-Up Protected: Will Withstand 0.5A Reverse Current
- Input Will Withstand Negative Inputs Up to 5V
- ESD Protected 4 kV
- Pin-compatible with TC426/TC427/TC428 and TC4426/TC4427/TC4428
- Space-saving 8-Pin MSOP and 8-Pin 6x5 DFN Packages

#### Applications:

- Switch Mode Power Supplies
- · Line Drivers
- · Pulse Transformer Drive

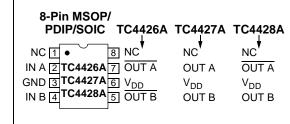
#### **General Description:**

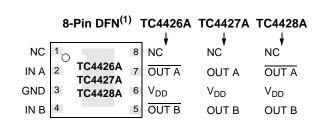
The TC4426A/TC4427A/TC4428A are improved versions of the earlier TC4426/TC4427/TC4428 family of MOSFET drivers. In addition to matched rise and fall times, the TC4426A/TC4427A/TC4428A devices have matched leading and falling edge propagation delay times.

These devices are highly latch-up resistant under any conditions within their power and voltage ratings. They are not subject to damage when up to 5V of noise spiking (of either polarity) occurs on the ground pin. They can accept, without damage or logic upset, up to 500 mA of reverse current (of either polarity) being forced back into their outputs. All terminals are fully protected against Electrostatic Discharge (ESD) up to 4 kV.

The TC4426A/TC4427A/TC4428A MOSFET drivers can easily charge/discharge 1000 pF gate capacitances in under 30 ns. These devices provide low enough impedances in both the on and off states to ensure the MOSFET's intended state will not be affected, even by large transients.

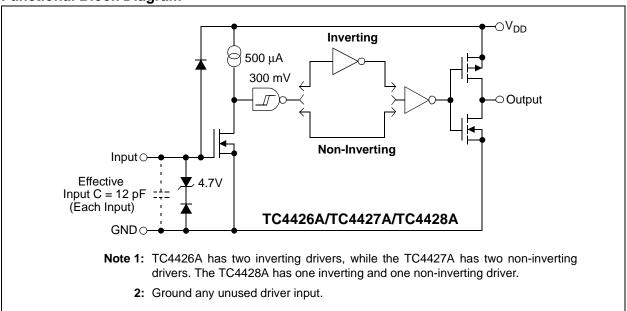
#### Package Types





Note 1: Exposed pad of the DFN package is electrically isolated.

#### **Functional Block Diagram**



# 1.0 ELECTRICAL CHARACTERISTICS

#### **Absolute Maximum Ratings†**

† **Notice:** Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions above those indicated in the operation sections of the specifications is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

#### **DC CHARACTERISTICS**

<b>Electrical Specifications:</b> Unless otherwise noted, over operating temperature range with $4.5V \le V_{DD} \le 18V$ .									
Parameters	Sym	Min	Тур	Max	Units	Conditions			
Input									
Logic '1', High Input Voltage	V <sub>IH</sub>	2.4	_	_	V				
Logic '0', Low Input Voltage	V <sub>IL</sub>	_	_	0.8	V				
Input Current	I <sub>IN</sub>	-1.0 -10	_	+1.0 +10	μА	$0V \le V_{IN} \le V_{DD}$			
Output				•	•				
High Output Voltage	V <sub>OH</sub>	V <sub>DD</sub> – 0.025	_	_	V	DC Test			
Low Output Voltage	V <sub>OL</sub>	_	_	0.025	V	DC Test			
Output Resistance	R <sub>O</sub>	_ _ _ _	7 7 8 8	9 10 11 12	Ω	$I_{OUT} = 10 \text{ mA}, V_{DD} = 18V, T_A = +25^{\circ}\text{C}$ $0^{\circ}\text{C} \le T_A \le +70^{\circ}\text{C}$ $-40^{\circ}\text{C} \le T_A \le +85^{\circ}\text{C}$ $-40^{\circ}\text{C} \le T_A \le +125^{\circ}\text{C}$			
Peak Output Current	I <sub>PK</sub>	_	1.5	_	Α	V <sub>DD</sub> = 18V			
Latch-Up Protection Withstand Reverse Current	I <sub>REV</sub>	_	> 0.5	_	Α	Duty cycle $\leq$ 2%, t $\leq$ 300 µsec $V_{DD}$ = 18V			
Switching Time (Note 1)									
Rise Time	t <sub>R</sub>	_ _ _ _	25 27 29 30	35 40 40 40	ns	$\begin{split} T_A &= +25^{\circ}C \\ 0^{\circ}C &\leq T_A \leq +70^{\circ}C \\ -40^{\circ}C &\leq T_A \leq +85^{\circ}C \\ -40^{\circ}C &\leq T_A \leq +125^{\circ}C, \text{ Figure 4-1} \end{split}$			
Fall Time	t <sub>F</sub>	_ _ _ _	25 27 29 30	35 40 40 40	ns	$T_A = +25^{\circ}C$ $0^{\circ}C \le T_A \le +70^{\circ}C$ $-40^{\circ}C \le T_A \le +85^{\circ}C$ $-40^{\circ}C \le T_A \le +125^{\circ}C$ , Figure 4-1			
Delay Time	t <sub>D1</sub>	- - - -	30 33 35 38	35 40 45 50	ns	$\begin{array}{l} T_A = +25^{\circ}C \\ 0^{\circ}C \leq T_A \leq +70^{\circ}C \\ -40^{\circ}C \leq T_A \leq +85^{\circ}C \\ -40^{\circ}C \leq T_A \leq +125^{\circ}C, \mbox{ Figure 4-1} \end{array}$			
Delay Time	t <sub>D2</sub>	_ _ _ _	30 33 35 38	35 40 45 50	ns	$T_A = +25^{\circ}C$ $0^{\circ}C \le T_A \le +70^{\circ}C$ $-40^{\circ}C \le T_A \le +85^{\circ}C$ $-40^{\circ}C \le T_A \le +125^{\circ}C$ , Figure 4-1			
Power Supply									
Power Supply Current	I <sub>S</sub>	_	1.0 0.1	2.0 0.2	mA	$V_{IN} = 3V$ (Both inputs) $V_{IN} = 0V$ (Both inputs), $V_{DD} = 18V$			

Note 1: Switching times ensured by design.

2: Package power dissipation is dependent on the copper pad area on the PCB.

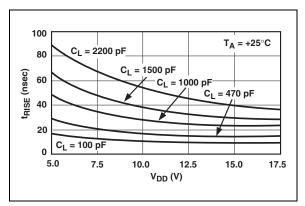
#### **TEMPERATURE CHARACTERISTICS**

<b>Electrical Specifications:</b> Unless otherwise noted, all parameters apply with 4.5V ≤ V <sub>DD</sub> ≤ 18V.									
Parameters	Sym	Min	Тур	Max	Units	Conditions			
Temperature Ranges									
Specified Temperature Range (C)	T <sub>A</sub>	0	_	+70	°C				
Specified Temperature Range (E)	T <sub>A</sub>	-40	_	+85	°C				
Specified Temperature Range (V)	T <sub>A</sub>	-40	_	+125	°C				
Maximum Junction Temperature	TJ	_	_	+150	°C				
Storage Temperature Range	T <sub>A</sub>	-65	_	+150	°C				
Package Thermal Resistances									
Thermal Resistance, 8L-6x5 DFN	$\theta_{JA}$	_	33.2	_	°C/W				
Thermal Resistance, 8L-MSOP	$\theta_{JA}$	_	206	_	°C/W				
Thermal Resistance, 8L-PDIP	$\theta_{JA}$	_	125	_	°C/W				
Thermal Resistance, 8L-SOIC	$\theta_{JA}$	_	155	_	°C/W				

#### 2.0 TYPICAL PERFORMANCE CURVES

**Note:** The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

**Note:** Unless otherwise indicated, over operating temperature range with  $4.5V \le V_{DD} \le 18V$ .



**FIGURE 2-1:** Rise Time vs. Supply Voltage.

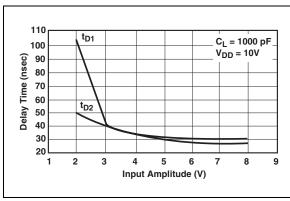
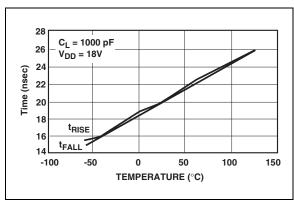


FIGURE 2-2: Delay Time vs. Input Amplitude.



**FIGURE 2-3:** Rise and Fall Times vs. Temperature.

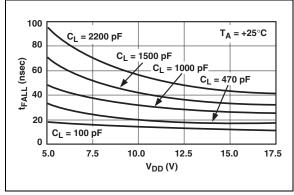
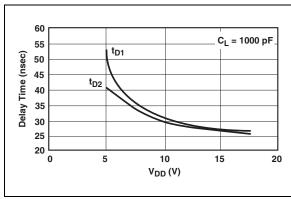
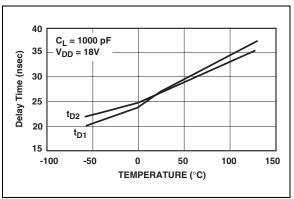


FIGURE 2-4: Fall Time vs. Supply Voltage.



**FIGURE 2-5:** Propagation Delay Time vs. Supply Voltage.



**FIGURE 2-6:** Propagation Delay Time vs. Temperature.

**Note:** Unless otherwise indicated, over operating temperature range with  $4.5V \le V_{DD} \le 18V$ .

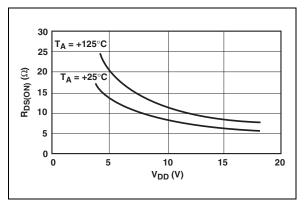


FIGURE 2-7: Resistance.

High-State Output

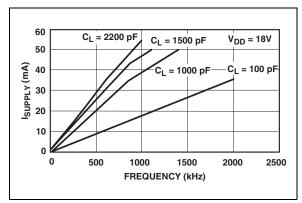


FIGURE 2-8: Frequency.

Supply Current vs.

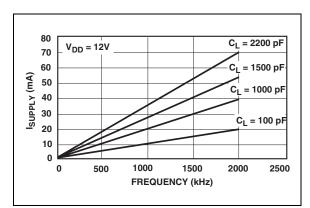
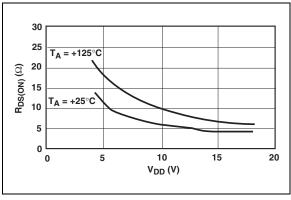


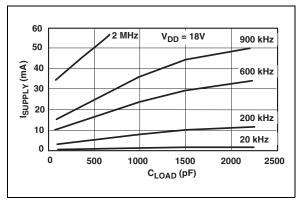
FIGURE 2-9: Frequency.

Supply Current vs.



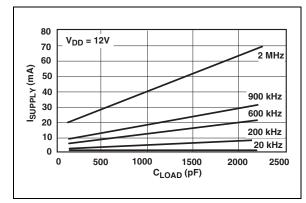
**FIGURE 2-10:** Resistance.

Low-State Output



**FIGURE 2-11:** Capacitive Load.

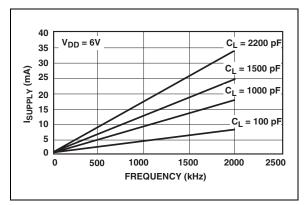
Supply Current vs.



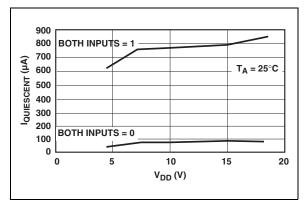
**FIGURE 2-12:** Capacitive Load.

Supply Current vs.

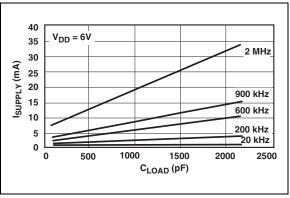
**Note:** Unless otherwise indicated, over operating temperature range with  $4.5V \le V_{DD} \le 18V$ .



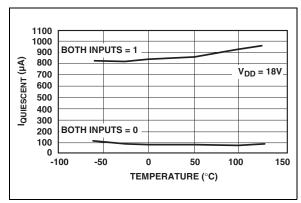
**FIGURE 2-13:** Supply Current vs. Frequency.



**FIGURE 2-14:** Quiescent Supply Current vs. Voltage.



**FIGURE 2-15:** Supply Current vs. Capacitive Load.



**FIGURE 2-16:** Quiescent Supply Current vs. Temperature.

#### 3.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 3-1.

TABLE 3-1: PIN FUNCTION TABLE

8-Pin PDIP/ MSOP/SOIC	8-Pin DFN	Symbol	Description
1	1	NC	No connection
2	2	IN A	Input A
3	3	GND	Ground
4	4	IN B	Input B
5	5	OUT B	Output B
6	6	V <sub>DD</sub>	Supply input
7	7	OUT A	Output A
8	8	NC	No connection
_	PAD	NC	Exposed Metal Pad

Note 1: Duplicate pins must be connected for proper operation.

#### 3.1 Inputs A and B

MOSFET driver inputs A and B are high-impedance, TTL/CMOS compatible inputs. These inputs also have 300 mV of hysteresis between the high and low thresholds that prevents output glitching, even when the rise and fall time of the input signal is very slow.

#### 3.2 Ground (GND)

The ground pin is the return path for both the bias current and the high peak current that discharges the external load capacitance. The ground pin should be tied into a ground plane or have a very short trace to the bias supply source return.

#### 3.3 Output A and B

MOSFET driver outputs A and B are low-impedance, CMOS push-pull style outputs. The pull-down and pull-up devices are of equal strength, making the rise and fall times equivalent.

#### 3.4 Supply Input (V<sub>DD</sub>)

The  $V_{DD}$  input is the bias supply for the MOSFET driver and is rated for 4.5V to 18V, with respect to the ground pin. The  $V_{DD}$  input should be bypassed with local ceramic capacitors. The value of these capacitors should be chosen based on the capacitive load that is being driven.

#### 3.5 Exposed Metal Pad

The exposed metal pad of the 6x5 DFN package is not internally connected to any potential. Therefore, this pad can be connected to a ground plane or other copper plane on a printed circuit board, to aid in heat removal from the package.

#### 4.0 APPLICATIONS INFORMATION

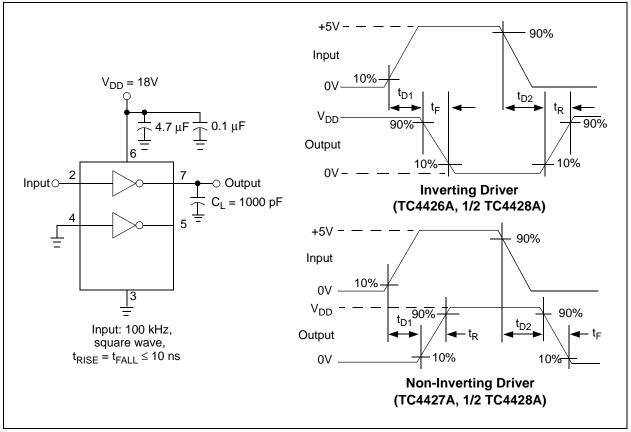
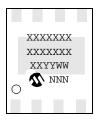


FIGURE 4-1: Switching Time Test Circuit.

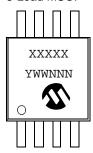
#### 5.0 PACKAGING INFORMATION

#### 5.1 Package Marking Information





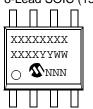
8-Lead MSOP



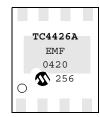
8-Lead PDIP (300 mil)



8-Lead SOIC (150 mil)



Example:



Example:



Example:







Legend: XX...X Customer specific information\*

YY Year code (last 2 digits of calendar year)
WW Week code (week of January 1 is week '01')

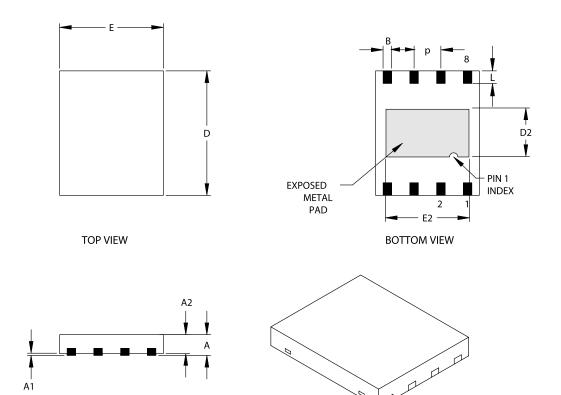
NNN Alphanumeric traceability code

Note:

In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line thus limiting the number of available characters for customer specific information.

<sup>\*</sup> Standard marking consists of Microchip part number, year code, week code, traceability code (facility code, mask rev#, and assembly code).

#### 8-Lead Plastic Dual Flat No Lead Package (MF) 6x5 mm Body (DFN-S) - Saw Singulated



	Units		INCHES		М	ILLIMETERS*	
Dimension Lim	its	MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	р		.050 BSC		1.27 BSC		
Overall Height	Α	.033	.035	.037	0.85	0.90	0.95
Package Thickness	A2	.031	.035	.037	0.80	0.89	0.95
Standoff	A1	.000	.0004	.002	0.00	0.01	0.05
Base Thickness	A3	.007	.008	.009	0.17	0.20	0.23
Overall Length	Е	.195	.197	.199	4.95	5.00	5.05
Exposed Pad Length	E2	.152	.157	.163	3.85	4.00	4.15
Overall Width	D	.234	.236	.238	5.95	6.00	6.05
Exposed Pad Width	D2	.089	.091	.093	2.25	2.30	2.35
Lead Width	В	.014	.016	.019	0.35	0.40	0.47
Lead Length	L	.024		.026	0.60		0.65

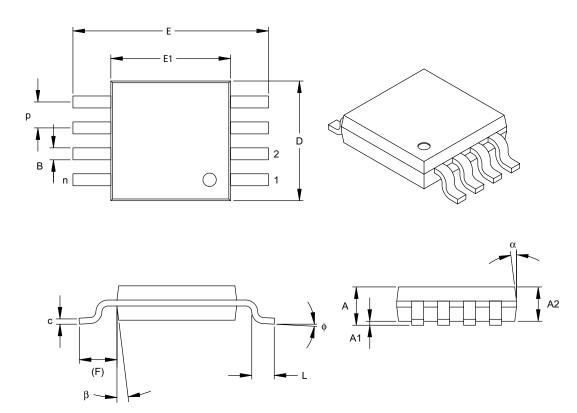
Notes:

JEDEC equivalent: MO-220

Drawing No. C04-122

Revised 11/3/03

#### 8-Lead Plastic Micro Small Outline Package (UA) (MSOP)



	Units		INCHES		М	ILLIMETERS	*
Dimension Lim	nits	MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	р		.026 BSC			0.65 BSC	
Overall Height	Α	-	-	.043	-	-	1.10
Molded Package Thickness	A2	.030	.033	.037	0.75	0.85	0.95
Standoff	A1	.000	-	.006	0.00	ı	0.15
Overall Width	E		.193 TYP.			4.90 BSC	
Molded Package Width	E1		.118 BSC			3.00 BSC	
Overall Length	D		.118 BSC			3.00 BSC	
Foot Length	L	.016	.024	.031	0.40	0.60	0.80
Footprint (Reference)	F		.037 REF		0.95 REF		
Foot Angle	ф	0°	-	8°	0°	-	8°
Lead Thickness	С	.003	.006	.009	0.08	-	0.23
Lead Width	В	.009	.012	.016	0.22	-	0.40
Mold Draft Angle Top	α	5°	-	15°	5°	•	15°
Mold Draft Angle Bottom	β	5°	-	15°	5°	-	15°

<sup>\*</sup>Controlling Parameter

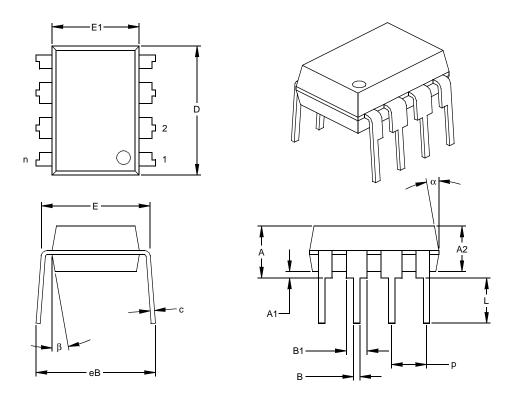
Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MO-187

Drawing No. C04-111

### 8-Lead Plastic Dual In-line (PA) - 300 mil (PDIP)

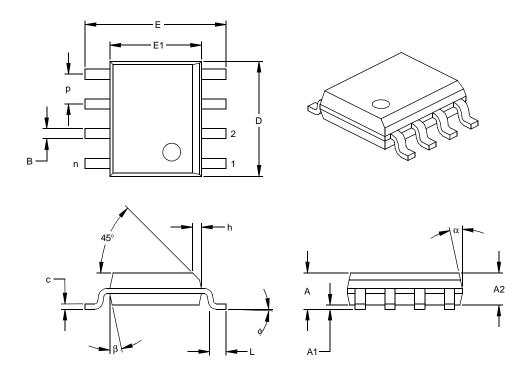


	Units		INCHES*		MILLIMETERS		
Dimensi	on Limits	MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	р		.100			2.54	
Top to Seating Plane	Α	.140	.155	.170	3.56	3.94	4.32
Molded Package Thickness	A2	.115	.130	.145	2.92	3.30	3.68
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	Е	.300	.313	.325	7.62	7.94	8.26
Molded Package Width	E1	.240	.250	.260	6.10	6.35	6.60
Overall Length	D	.360	.373	.385	9.14	9.46	9.78
Tip to Seating Plane	L	.125	.130	.135	3.18	3.30	3.43
Lead Thickness	С	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.045	.058	.070	1.14	1.46	1.78
Lower Lead Width	В	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing	§ eB	.310	.370	.430	7.87	9.40	10.92
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side. JEDEC Equivalent: MS-001 Drawing No. C04-018

<sup>\*</sup> Controlling Parameter § Significant Characteristic

### 8-Lead Plastic Small Outline (OA) - Narrow, 150 mil (SOIC)



		INCHES*		MILLIMETERS			
Dimension	Limits	MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	р		.050			1.27	
Overall Height	Α	.053	.061	.069	1.35	1.55	1.75
Molded Package Thickness	A2	.052	.056	.061	1.32	1.42	1.55
Standoff §	A1	.004	.007	.010	0.10	0.18	0.25
Overall Width	Е	.228	.237	.244	5.79	6.02	6.20
Molded Package Width	E1	.146	.154	.157	3.71	3.91	3.99
Overall Length	D	.189	.193	.197	4.80	4.90	5.00
Chamfer Distance	h	.010	.015	.020	0.25	0.38	0.51
Foot Length	Г	.019	.025	.030	0.48	0.62	0.76
Foot Angle	ф	0	4	8	0	4	8
Lead Thickness	С	.008	.009	.010	0.20	0.23	0.25
Lead Width	В	.013	.017	.020	0.33	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

<sup>\*</sup> Controlling Parameter

#### Notes

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side. JEDEC Equivalent: MS-012

Drawing No. C04-057

<sup>§</sup> Significant Characteristic

#### PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO. X	XX	XXX	<u>X</u>	Examples:	
Device Tempe Ran		Tape & Reel	PB Free	a) TC4426ACOA:	1.5A Dual Inverting MOSFET driver, 0°C to +70°C, 8LD SOIC package.
Device:	TC4426A: 1.5A Dual TC4427A: 1.5A Dual TC4428A: 1.5A Dual	MOSFET Driver,	Non-Inverting	b) TC4426AEOA:	1.5A Dual Inverting MOSFET driver, -40°C to +85°C, 8LD SOIC package.
Temperature Range:	C = 0°C to +70°C E = -40°C to +85° V = -40°C to +125		nly)	c) TC4426AEMF:	1.5A Dual Inverting MOSFET driver, -40°C to +85°C, 8LD DFN package.
	MF713 = Dual, Flat, (Tape and		n Body), 8-lead	a) TC4427ACPA:	1.5A Dual Non-Inverting MOSFET driver, 0°C to +70°C, 8LD PDIP package.
OA = Plastic SOIC, (150 n OA713 = Plastic SOIC, (150 n (Tape and Reel) UA = Plastic Micro Small (		IC, (150 mil Body) IC, (150 mil Body) Reel) ro Small Outline (l	mil Body), 8-lead mil Body), 8-lead Outline (MSOP), 8-lead	b) TC4427AEPA:	1.5A Dual Non-Inverting MOSFET driver, -40°C to +85°C, 8LD PDIP package.
UA713 = Plastic Micro Small Outline (MSOP), 8-lea (Tape and Reel)			visor), o-lead	c) TC4427AVMF713:	1.5A Dual Non-Inverting MOSFET driver, -40°C to +125°C, 8LD DFN package, Tape and Reel.
				a) TC4428AEPA:	1.5A Dual Complementary MOSFET driver, -40°C to +85°C, 8LD PDIP package.
				b) TC4428ACOA713:	1.5A Dual Complementary MOSFET driver, 0°C to +70°C 8LD SOIC package, Tape and Reel.
				c) TC4428AVMF:	1.5A Dual Complementary MOSFET driver, -40°C to +125°C, 8LD DFN package.

#### **Sales and Support**

#### **Data Sheets**

Products supported by a preliminary Data Sheet may have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

- 1. Your local Microchip sales office
- 2. The Microchip Corporate Literature Center U.S. FAX: (480) 792-7277
- 3. The Microchip Worldwide Site (www.microchip.com)

Please specify which device, revision of silicon and Data Sheet (include Literature #) you are using.

#### **Customer Notification System**

Register on our web site (www.microchip.com/cn) to receive the most current information on our products.

NOTES:

#### Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
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CERTIFIED BY DNV

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